

**WHAT IS CLAIMED IS:**

1. A manufacturing apparatus comprising:

a film formation chamber comprising an evaporation source opposing a substrate,  
5 means for moving the evaporation source in an X direction, and means for moving the substrate  
in a Y direction,

wherein a film is deposited on the substrate by repeating moving the evaporation source  
in the X direction and then moving the substrate in the Y direction at regular intervals.

10 2. The manufacturing apparatus according to claim 1, wherein a plurality of the  
evaporation source are provided and move in parallel to each other.

3. The manufacturing apparatus according to claim 1, wherein the evaporation source is  
reciprocated in the X direction.

15 4. The manufacturing apparatus according to any one of claim 1, wherein the substrate  
is reciprocated in the Y direction in a film formation chamber.

5. A manufacturing apparatus comprising:

20 a film formation chamber comprising means for moving a substrate in a Y direction;  
a setting chamber connected to the film formation chamber, the setting chamber  
comprising an evaporation source and means for moving the evaporation source in an X  
direction from the setting chamber into the film formation chamber,

25 wherein a film is deposited on the substrate by repeating moving the evaporation source  
in the X direction and then moving the substrate in the Y direction at regular intervals.

6. The manufacturing apparatus according to claim 5, wherein a container storing an  
evaporation material is set in the evaporation source without being exposed to an atmosphere  
outside of the setting chamber.

7. The manufacturing apparatus according to claim 5, wherein the setting chamber has a film thickness meter.

8. The manufacturing apparatus according to claim 5, wherein the film formation chamber and the setting chamber are connected to a vacuum discharge treatment chamber for vacuuming the chambers and have means for bringing in a material gas or a cleaning gas.

9. The manufacturing apparatus according to claim 5, wherein a plurality of the evaporation source are provided and move in parallel to each other.

10. The manufacturing apparatus according to claim 5, wherein the evaporation source is reciprocated in the X direction.

11. The manufacturing apparatus according to any one of claim 5, wherein the substrate is reciprocated in the Y direction in a film formation chamber.

12. A manufacturing apparatus comprising:  
a film formation chamber comprising a first evaporation source provided to be opposite to a substrate, first means for moving the first evaporation source in an X direction, a second evaporation source provided to be opposite to the substrate, second means for moving the second evaporation source in the X direction, and means for moving the substrate in a Y direction,

wherein a film is deposited by repeatedly moving the substrate in the Y direction at regular intervals while making a movement speed of the first evaporation source in the X direction and a movement speed of the second evaporation source in the X direction different.

13. The manufacturing apparatus according to claim 12, wherein film thickness meters of adjacent first and second evaporation sources are disposed alternately so as to sandwich a movement pathway of the substrate.

14. The manufacturing apparatus according to claim 12, wherein the first and second

evaporation sources are reciprocated in the X direction.

15. The manufacturing apparatus according to any one of claim 12, wherein the substrate is reciprocated in the Y direction in a film formation chamber.

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16. A manufacturing apparatus comprising:

a loading chamber;

a delivery chamber connected to the loading chamber; and

a plurality of film formation chambers connected to the delivery chambers,

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wherein each of the plurality of the film formation chambers comprises a plurality of evaporation sources, means for moving the evaporation source in an X direction, and means for moving a substrate in a Y direction, and

wherein a film is deposited on the substrate by moving or reciprocating the evaporation sources in the X direction while moving the substrate in the Y direction at a constant speed.

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17. A method for manufacturing a semiconductor device comprising:

depositing a film over a substrate by repeating moving an evaporation source in an X direction and then moving the substrate in a Y direction at regular intervals.

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